Notice for TAIYO YUDEN products

Please read this notice before using the TAIYO YUDEN products.

! REMINDERS

Product information in this catalog is as of October 2015. All of the contents specified herein are subject to change without notice due to technical improvements, etc. Therefore, please check for the latest information carefully before practical application or usage of the Products.

Please note that TAIYO YUDEN CO., LTD. shall not be responsible for any defects in products or equipment incorporating such products, which are caused under the conditions other than those specified in this catalog or individual specification.

Please contact TAIYO YUDEN CO., LTD. for further details of product specifications as the individual specification is available.

Please conduct validation and verification of products in actual condition of mounting and operating environment before commercial shipment of the equipment.

All electronic components or functional modules listed in this catalog are developed, designed and intended for use in general electronics equipment.(for AV, office automation, household, office supply, information service, telecommunications, (such as mobile phone or PC) etc.). Before incorporating the components or devices into any equipment in the field such as transportation,(automotive control, train control, ship control), transportation signal, disaster prevention, medical, public information network (telephone exchange, base station) etc. which may have direct influence to harm or injure a human body, please contact TAIYO YUDEN CO., LTD. for more detail in advance.

Do not incorporate the products into any equipment in fields such as aerospace, aviation, nuclear control, submarine system, military, etc. where higher safety and reliability are especially required.

In addition, even electronic components or functional modules that are used for the general electronic equipment, if the equipment or the electric circuit require high safety or reliability function or performances, a sufficient reliability evaluation check for safety shall be performed before commercial shipment and moreover, due consideration to install a protective circuit is strongly recommended at customer's design stage.

The contents of this catalog are applicable to the products which are purchased from our sales offices or distributors (so called "TAIYO YUDEN' s official sales channel").
It is only applicable to the products purchased from any of TAIYO YUDEN', a official sales channel

It is only applicable to the products purchased from any of TAIYO YUDEN's official sales channel.

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Caution for export

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TAIYO YUDEN 2016

WIRE-WOUND CHIP POWER INDUCTORS(BR SERIES)



PARTS NUMB	ER			* Operating Te	mp.:-40 ~ +105℃
	L 2 5 1 8 T 2 R 3 4 5	 M △ 6)	∆ ⑦	Δ	$\Delta =$ Blank space
①Series name				④Packaging	
Code	Series name			Code	
BR	Wire-Wound chip power inductor	 _		Т	
②Characteristics	5	_		⑤Nominal indu	ctance
Code	Characteristics			Code	No
FL		-		(example)	NO
ΔL	Low profile			R20	
HL				1R0	
ΔC	High current	-		100	

③Dimensions(L×W)

Type(inch)	Dimensions (L×W)[mm]
1608(0603)	1.6 × 0.8
2012(0805)	2.0 × 1.25
2016(0806)	2.0×1.6
2518(1007)	2.5 × 1.8
3225(1210)	3.2 × 2.5
	1608(0603) 2012(0805) 2016(0806) 2518(1007)

* Operating Temp.:-40 \sim +105°C (Including self-generated heat)

Code	Packaging
Т	Taping

Code (example)	Nominal inductance[μ H]
R20	0.2
1R0	1.0
100	10
101	100

ℜR=Decimal point

(6)Inductance tolerance

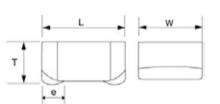
Code	Inductance tolerance
К	±10%
М	±20%

 \bigcirc Internal code

Recommended Land Patterns

Surface Mounting

STANDARD EXTERNAL DIMENSIONS / STANDARD QUANTITY



Applicable soldering process to t	Туре	A	В	С
	1608	0.55	0.70	1.00
C	2012	0.60	1.00	1.45
	2016	0.60	1.00	1.80
•	2518	0.60	1.50	2.00
ABA	3225	0.85	1.70	2.70

Unit:mm

Туре		W	т	е	Standard qu	iantity[pcs]	
туре	L	vv	-	e	Paper tape	Embossed tape	
BR L1608	1.6±0.2	0.8 ± 0.2	0.7 max	0.45 ± 0.15	_	3000	
DIVETOOD	(0.063 ± 0.008)	(0.031 ± 0.008)	(0.028 max)	(0.016 ± 0.006)		3000	
BR C1608	1.6 ± 0.2	0.8 ± 0.2	0.8 ± 0.2	0.45 ± 0.15	_	3000	
BIT 01000	(0.063 ± 0.008)	(0.031 ± 0.008)	(0.031 ± 0.008)	(0.016 ± 0.006)		5000	
BR L2012	2.0±0.2	1.25 ± 0.2	1.0 max	0.5 ± 0.2	_	3000	
DR L2012	(0.079 ± 0.008)	(0.049 ± 0.008)	(0.040 max)	(0.020 ± 0.008)		3000	
BR C2012	2.0±0.2	1.25 ± 0.2	1.4 max	0.5 ± 0.2	_	2000	
BR 02012	(0.079 ± 0.008)	(0.049 ± 0.008)	(0.056 max)	(0.020 ± 0.008)		2000	
BR C2016	2.0±0.2	1.6 ± 0.2	1.6 ± 0.2	0.5 ± 0.2	_	2000	
BR 02010	(0.079 ± 0.008)	(0.063 ± 0.008)	(0.063 ± 0.008)	(0.020 ± 0.008)		2000	
BRFL2518	2.5 ± 0.2	1.8 ± 0.2	1.0 max	0.5 ± 0.2	_	3000	
DRI L2310	(0.098 ± 0.008)	(0.071 ± 0.008)	(0.040 max)	(0.020 ± 0.008)		3000	
BR L2518	2.5 ± 0.2	1.8 ± 0.2	1.2 max	0.5 ± 0.2	_	3000	
DR LZJIO	(0.098 ± 0.008)	(0.071 ± 0.008)	(0.048 max)	(0.020 ± 0.008)	_	3000	
BRHL2518	2.5±0.2	1.8±0.2	1.5 max	0.5±0.2		2000	
DRHLZJIS	(0.098 ± 0.008)	(0.071 ± 0.008)	(0.060 max)	(0.020 ± 0.008)	_	2000	
PD 02519	2.5±0.2	1.8±0.2	1.8±0.2	0.5±0.2	_	2000	
BR C2518	(0.098 ± 0.008)	(0.071 ± 0.008)	(0.071 ± 0.008)	(0.020 ± 0.008)	—	2000	
DD 1 2225	3.2±0.2	2.5±0.2	1.7 max	0.75±0.2		2000	
BR L3225	(0.126 ± 0.008)	(0.098 ± 0.008)	(0.068 max)	(0.03 ± 0.008)	—	2000	
						Unit:mm(inch)	

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

TAIYO YUDEN 2016

1608 (0603) TYPE

	EHS	Nominal inductance [Inductance tolerance	Self-resonant	DC Resistance [Ω](±30%)	Rated curren	Management	
Parts number				frequency [MHz](min.)		Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]
BR L1608T1R0M	RoHS	1.0	±20%	700	0.230	510	650	1.0
BR L1608T1R5M	RoHS	1.5	±20%	600	0.280	440	590	1.0
BR L1608T2R2M	RoHS	2.2	±20%	400	0.400	360	500	1.0
BR L1608T3R3M	RoHS	3.3	±20%	300	0.650	290	390	1.0
BR L1608T4R7M	RoHS	4.7	±20%	150	1.00	240	310	1.0
BR L1608T6R8M	RoHS	6.8	±20%	100	1.64	200	250	1.0
BR L1608T100M	RoHS	10	±20%	45	2.00	170	220	1.0
BR L1608T150M	RoHS	15	±20%	32	2.56	150	200	1.0

		Nominal inductance		Self-resonant		Rated curren	Measuring	
Parts number	EHS	[µH]	Inductance tolerance	frequency [MHz](min.)	DC Resistance $[\Omega](\pm 30\%)$	Saturation current Idc1	Temperature rise current Idc2	frequency[MHz]
BR C1608TR43M 6	RoHS	0.43	±20%	740	0.082	1,400	1,100	6.0
BR C1608TR50M 6	RoHS	0.50	±20%	710	0.090	1,200	1,050	6.0
BR C1608TR60M 6	RoHS	0.60	±20%	630	0.099	1,100	940	6.0
BR C1608TR72M 6	RoHS	0.72	±20%	600	0.144	1,000	810	6.0
BR C1608TR82M 6	RoHS	0.82	±20%	560	0.176	950	730	6.0
BR C1608T1R0M 6	RoHS	1.0	±20%	550	0.188	890	680	6.0

		$ \begin{array}{c c} EHS & Nominal inductance \\ [\muH] \end{array} & Inductance tolerance & Self-resonant \\ frequency \\ [MHz](min.) \end{array} & DC Resistan \\ [\Omega](\pm 309) \end{array} $	al inductance Inductance tolerance frequency DC Resis	Self-resonant	DC Desistance	Rated curren	Measuring	
Parts number	EHS			Inductance tolerance frequency [O1(+20%)]		Saturation current Idc1	Temperature rise current Idc2	frequency[MHz]
BR C1608TR20M	RoHS	0.20	±20%	400	0.060	1,750	980	7.96
BR C1608TR35M	RoHS	0.35	±20%	300	0.080	1,400	810	7.96
BR C1608TR45M	RoHS	0.45	±20%	200	0.090	1,250	800	7.96
BR C1608TR56M	RoHS	0.56	±20%	170	0.095	1,150	760	7.96
BR C1608TR77M	RoHS	0.77	±20%	150	0.110	1,000	660	7.96
BR C1608T1R0M	RoHS	1.0	±20%	140	0.180	850	520	7.96
BR C1608T1R5M	RoHS	1.5	±20%	120	0.300	700	410	7.96
BR C1608T2R2M	RoHS	2.2	±20%	100	0.550	550	280	7.96

2012(0805)TYPE

Parts number	EHS	Nominal inductance [μ H]	Inductance tolerance	Self-resonant frequency [MHz] (min.)	DC Resistance	Rated curren	Measuring	
					$[\Omega](\pm 30\%)$	Saturation current Idc1	Temperature rise current Idc2	frequency[MHz]
BR L2012TR47M 6	RoHS	0.47	±20%	500	0.048	1,500	1,900	6.0
BR L2012T1R0M 6	RoHS	1.0	±20%	400	0.108	1,050	1,230	6.0
BR L2012T2R2MD6	RoHS	2.2	±20%	250	0.184	680	950	6.0

		Nominal inductance		Self-resonant	DC Resistance	Rated curren	t ※)[mA]	Manager
Parts number	EHS	[μ H]	Inductance tolerance	frequency [MHz](min.)	$[\Omega](\pm 30\%)$	Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]
BR L2012TR47M	RoHS	0.47	±20%	350	0.090	1,100	1,050	7.96
BR L2012T1R0M	RoHS	1.0	±20%	300	0.135	850	850	7.96
BR L2012T1R5M	RoHS	1.5	±20%	250	0.180	700	750	7.96
BR L2012T2R2M	RoHS	2.2	±20%	200	0.300	600	550	7.96
BR L2012T3R3M	RoHS	3.3	±20%	190	0.500	490	440	7.96
BR L2012T4R7M	RoHS	4.7	±20%	150	0.550	340	400	7.96
BR L2012T6R8M	RoHS	6.8	±20%	60	0.750	290	350	7.96
BR L2012T100M	RoHS	10	±20%	30	0.850	270	330	2.52
BR L2012T150M	RoHS	15	±20%	15	1.00	220	300	2.52
BR L2012T220M	RoHS	22	±20%	13	1.30	190	270	2.52
BR L2012T330M	RoHS	33	±20%	8.0	2.00	150	220	2.52
BR L2012T470M	RoHS	47	±20%	7.0	3.50	125	160	2.52
BR L2012T680M	RoHS	68	±20%	6.5	5.80	100	110	2.52
BR L2012T101M	RoHS	100	±20%	6.0	7.70	85	85	0.796

		Nominal inductance		Self-resonant DC Resistance		Rated curren	Measuring	
Parts number	EHS	[µ H]	Inductance tolerance	frequency [MHz](min.)	$[\Omega](\pm 30\%)$	Saturation current Idc1	Temperature rise current Idc2	frequency[MHz]
BR C2012T1R0M	RoHS	1.0	±20%	490	0.060	1,500	1,400	1.0
BR C2012T1R5MD	RoHS	1.5	±20%	390	0.090	1,200	1,100	1.0
BR C2012T2R2MD	RoHS	2.2	±20%	350	0.110	1,100	1,000	1.0
BR C2012T3R3MD	RoHS	3.3	±20%	300	0.170	800	870	1.0
BR C2012T4R7MD	RoHS	4.7	±20%	250	0.265	700	600	1.0

%) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30%. (at 20°C)

X) The temperature rise current value (Idc2) is the DC current value having temperature increase up to 40°C. (at 20°C)

2016 (0806) TYPE

		Manufact for device on a		Self-resonant	DO De sistemas	Rated curren	t 💥) [mA]	Manager
Parts number	EHS	Nominal inductance [µ H]	Inductance tolerance	frequency [MHz] (min.)	DC Resistance $[\Omega](\pm 30\%)$	Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]
BR C2016T1R0M	RoHS	1.0	±20%	450	0.085	1,350	1,100	0.10
BR C2016T1R5M	RoHS	1.5	±20%	370	0.150	1,100	820	0.10
BR C2016T2R2M	RoHS	2.2	±20%	250	0.180	910	760	0.10
BR C2016T3R3M	RoHS	3.3	±20%	140	0.220	740	680	0.10
BR C2016T4R7M	RoHS	4.7	±20%	78	0.270	660	610	0.10
BR C2016T6R8M	RoHS	6.8	±20%	39	0.330	550	560	0.10
BR C2016T100[]	RoHS	10	±10%, ±20%	35	0.400	450	520	0.10
BR C2016T150[]	RoHS	15	±10%, ±20%	28	0.600	400	410	0.10
BR C2016T220[]	RoHS	22	±10%, ±20%	24	1.00	310	310	0.10
BR C2016T330[]	RoHS	33	±10%, ±20%	13	1.70	270	240	0.10
BR C2016T470[]	RoHS	47	±10%, ±20%	11	2.20	210	210	0.10
BR C2016T680[]	RoHS	68	±10%, ±20%	8	2.80	200	190	0.10
BR C2016T101[]	RoHS	100	±10%, ±20%	7	3.40	140	170	0.10

2518(1007) TYPE

		New York Instruction		Self-resonant	DC Resistance	Rated current ※) [mA]		Measuring
Parts number	EHS	Nominal inductance [μΗ]	Inductance tolerance	e frequency [MHz] (min.)	$[\Omega](\pm 30\%)$	Saturation current Idc1	Temperature rise current Idc2	frequency[MHz]
BRFL2518T1R0M	RoHS	1.0	±20%	130	0.090	1,200	1,200	1.0
BRFL2518T1R5M	RoHS	1.5	±20%	100	0.110	1,100	1,000	1.0
BRFL2518T2R2M	RoHS	2.2	±20%	80	0.130	850	950	1.0
BRFL2518T3R3M	RoHS	3.3	±20%	70	0.220	700	700	1.0
BRFL2518T4R7M	RoHS	4.7	±20%	60	0.330	650	650	1.0

		Nominal inductance	inductor of		Self-resonant DC Resistance		Rated current 💥) [mA]		
Parts number	EHS	[µ H]	Inductance tolerance	frequency $[MHz]$ (min.) $[\Omega](\pm 30\%)$	Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]		
BR L2518T1R0M	RoHS	1.0	±20%	130	0.080	1,600	1,000	7.96	
BR L2518T1R5M	RoHS	1.5	±20%	100	0.100	1,200	920	7.96	
BR L2518T2R2M	RoHS	2.2	±20%	80	0.135	1,000	850	7.96	
BR L2518T3R3M	RoHS	3.3	±20%	70	0.300	800	580	7.96	
BR L2518T4R7M	RoHS	4.7	±20%	60	0.400	700	470	7.96	

		Nominal inductance		Self-resonant DC Resistance		Rated curren	Measuring	
Parts number	EHS	[µ H]	Inductance tolerance	frequency [MHz] (min.)	$[\Omega](\pm 30\%)$	Saturation current Idc1	Temperature rise current Idc2	frequency[MHz]
BRHL2518T1R0M	RoHS	1.0	±20%	400	0.055	2,000	1,400	1.0
BRHL2518T1R5M	RoHS	1.5	±20%	350	0.085	1,700	1,100	1.0
BRHL2518T2R2M	RoHS	2.2	±20%	300	0.115	1,500	1,000	1.0
BRHL2518T3R3MD	RoHS	3.3	±20%	200	0.165	1,200	800	1.0
BRHL2518T4R7MD	RoHS	4.7	±20%	150	0.245	1,100	750	1.0

		New Seed Scalescher er		Self-resonant	DO De distance	Rated curren	t ※)[mA]	Manageria
Parts number	EHS	Nominal inductance [μ H]	Inductance tolerance	frequency [MHz](min.)	DC Resistance $[\Omega](\pm 30\%)$	Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]
BR C2518T1R0M	RoHS	1.0	±20%	280	0.050	2,550	1,650	1.0
BR C2518T1R5M	RoHS	1.5	±20%	230	0.080	2,100	1,300	1.0
BR C2518T2R2M	RoHS	2.2	±20%	200	0.120	1,800	1,000	1.0
BR C2518T3R3M	RoHS	3.3	±20%	150	0.175	1,450	860	1.0
BR C2518T4R7M	RoHS	4.7	±20%	100	0.230	1,250	750	1.0
BR C2518T6R8M	RoHS	6.8	±20%	45	0.280	1,050	680	1.0
BR C2518T100[]	RoHS	10	±10%, ±20%	20	0.350	890	610	1.0
BR C2518T150[]	RoHS	15	±10%, ±20%	13	0.430	760	550	1.0
BR C2518T220[]	RoHS	22	±10%, ±20%	10	0.560	640	490	1.0
BR C2518T330[]	RoHS	33	±10%, ±20%	8	0.850	560	390	1.0
BR C2518T470[]	RoHS	47	±10%, ±20%	6.5	1.45	410	300	1.0
BR C2518T680[]	RoHS	68	±10%, ±20%	5.5	2.40	340	230	1.0
BR C2518T101	RoHS	100	±10%, ±20%	4.5	3.60	300	190	1.0

• [] Please specify the inductance tolerance code. (M or K)

%) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30%. (at 20 $^{\circ}\text{C})$

%) The temperature rise current value (Idc2) is the DC current value having temperature increase up to 40°C. (at 20°C)

3225(1210)TYPE

		New York in dealers a		Self-resonant frequency [MHz] (min.)	DC Resistance [Ω](±30%)	Rated curren	Measuring	
Parts number	EHS	Nominal inductance [µ H]	Inductance tolerance			Saturation current Idc1	Temperature rise current Idc2	frequency[MHz]
BR L3225TR27M	RoHS	0.27	±20%	390	0.022	4,500	2,850	7.96
BR L3225TR36M	RoHS	0.36	±20%	350	0.025	4,300	2,750	7.96
BR L3225TR51M	RoHS	0.51	±20%	270	0.029	3,600	2,550	7.96

		New tool to dealers		Self-resonant	DC Resistance	Rated curren	t 💥) [mA]	Manageria
Parts number	EHS	Nominal inductance [µ H]	Inductance tolerance	frequency [MHz](min.)	$[\Omega](\pm 20\%)$	Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]
BR L3225T1R0M	RoHS	1.0	±20%	220	0.043	2,400	2,200	0.1
BR L3225T1R5M	RoHS	1.5	±20%	170	0.045	2,200	1,750	0.1
BR L3225T2R2M	RoHS	2.2	±20%	150	0.065	1,850	1,600	0.1
BR L3225T3R3M	RoHS	3.3	±20%	140	0.120	1,450	1,200	0.1
BR L3225T4R7M	RoHS	4.7	±20%	120	0.180	1,300	1,000	0.1
BR L3225T6R8M	RoHS	6.8	±20%	90	0.270	1,050	770	0.1
BR L3225T100[]	RoHS	10	±10%, ±20%	70	0.350	900	700	0.1
BR L3225T150[]	RoHS	15	±10%, ±20%	20	0.570	700	530	0.1
BR L3225T220[]	RoHS	22	±10%, ±20%	13	0.690	550	470	0.1
BR L3225T330[]	RoHS	33	±10%, ±20%	9	0.840	470	420	0.1
BR L3225T470[]	RoHS	47	±10%, ±20%	7	1.00	420	390	0.1
BR L3225T680[]	RoHS	68	±10%, ±20%	6	1.40	330	300	0.1
BR L3225T101	RoHS	100	±10%, ±20%	5	2.50	270	250	0.1

Please specify the inductance tolerance code. (M or K)

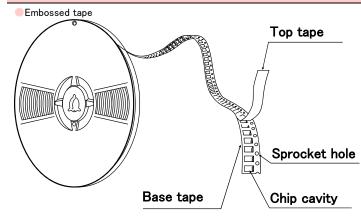
%) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30% (at 20°C) %) The temperature rise current value (Idc2) is the DC current value having temperature increase up to 40°C. (at 20°C)

WIRE-WOUND CHIP POWER INDUCTORS (BR SERIES)

PACKAGING

①Minimum Quantity		
Туре	Standard Qu	uantity [pcs]
Туре	Paper Tape	Embossed Tape
BR C1608	—	3,000
BR L1608	—	3,000
BR L2012	—	3,000
BR C2012	—	2,000
BR C2016	—	2,000
BR C2518	—	2,000
BRHL2518	—	2,000
BR L2518	-	3,000
BRFL2518	-	3,000
BR L3225	—	2,000

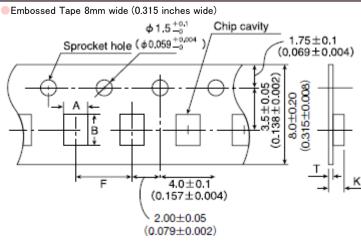
2 Tape Material



Chip Filled

(- 7 Chi	

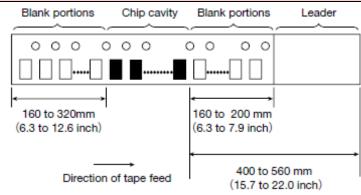
③Taping dimensions



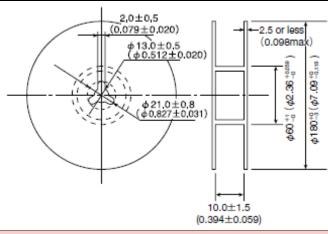


T	Chip	cavity	Insertion pitch	Tape th	ickness
Туре	A	В	F	Т	К
BR L1608	1.1±0.1	1.9 ± 0.1	4.0±0.1	0.2 ± 0.05	0.9 max
DR LI000	(0.043 ± 0.004)	(0.075 ± 0.004)	(0.157 ± 0.004)	(0.008 ± 0.002)	(0.035 max)
BR C1608	1.1±0.1	1.9 ± 0.1	4.0±0.1	0.25 ± 0.05	1.2 max
DR C1000	(0.043 ± 0.004)	(0.075 ± 0.004)	(0.157 ± 0.004)	(0.010 ± 0.002)	(0.047 max)
BR L2012	1.45 ± 0.1	2.2 ± 0.1	4.0±0.1	0.25 ± 0.05	1.2 max
DR L2012	(0.057 ± 0.004)	(0.087 ± 0.004)	(0.157±0.004)	(0.010 ± 0.002)	(0.047 max)
BR C2012	1.45 ± 0.1	2.37±0.1	4.0±0.1	0.25 ± 0.05	1.59 max
	(0.057 ± 0.004)	(0.093 ± 0.004)	(0.157 ± 0.004)	(0.010 ± 0.002)	(0.063 max)
BR C2016	1.75±0.1	2.1 ± 0.1	4.0±0.1	0.3 ± 0.05	1.9 max
	(0.069 ± 0.004)	(0.083 ± 0.004)	(0.157 ± 0.004)	(0.012 ± 0.002)	(0.075 max)
BRFL2518	2.3±0.1	2.8±0.1	4.0±0.1	0.25 ± 0.05	1.3 max
DRFLZJIO	(0.091 ± 0.004)	(0.110 ± 0.004)	(0.157 ± 0.004)	(0.010 ± 0.002)	(0.051 max)
BR L2518	2.3±0.1	2.8±0.1	4.0±0.1	0.3 ± 0.05	1.45 max
DR L2310	(0.091 ± 0.004)	(0.110 ± 0.004)	(0.157±0.004)	(0.012 ± 0.002)	(0.057 max)
BRHL2518	2.1 ± 0.1	2.8±0.1	4.0 ± 0.1	0.3 ± 0.05	1.7 max
	(0.083 ± 0.004)	(0.110 ± 0.004)	(0.157±0.004)	(0.012 ± 0.002)	(0.067 max)
BR C2518	2.15±0.1	2.7±0.1	4.0±0.1	0.3 ± 0.05	2.2 max
DR UZJIO	(0.085 ± 0.004)	(0.106 ± 0.004)	(0.157±0.004)	(0.012 ± 0.002)	(0.087 max)
BR L3225	2.8±0.1	3.5 ± 0.1	4.0 ± 0.1	0.25 ± 0.05	1.9 max
	(0.110 ± 0.004)	(0.138 ± 0.004)	(0.157 ± 0.004)	(0.010 ± 0.002)	(0.075 max)
					Unit:mm(inch)

4Leader and Blank portion

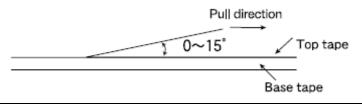


⑤Reel size



6 Top Tape Strength

The top tape requires a peel-off force of 0.2 to 0.7N in the direction of the arrow as illustrated below.





WIRE-WOUND CHIP POWER INDUCTORS (BR SERIES)

RELIABILITY DATA

1. Operating Tempe	1. Operating Temperature Range					
Specified Value	BR series	$-40 \sim +105^{\circ}$ C				
Test Methods and Remarks	Including self-generated heat					

2. Storage Tempera	Storage Temperature Range (after soldering)		
Specified Value	BR series −40~+85°C		
Test Methods and Remarks	Please refer the term of "7.Storage conditions" in Precautions.		

3. Rated current		
Specified Value	BR series	Within the specified tolerance

4. Inductance			
Specified Value	BR series		Within the specified tolerance
Test Methods and	Measuring equipment : LCR Meter (HP 4285A or equivalent)		HP 4285A or equivalent)
Remarks	Measuring frequency	: Specified frequency	

5. DC Resistance	5. DC Resistance		
Specified Value	BR series		Within the specified tolerance
Test Methods and Remarks	Measuring equipment	: DC ohmmeter	(HIOKI 3227 or equivalent)

6. Self resonance fr	equency		
Specified Value	BR series		Within the specified tolerance
Test Methods and Remarks	Measuring equipment	•	alyzer/material analyzer equivalent HP4191A, 4192A or equivalent)

7. Temperature cha	Temperature characteristic		
Specified Value	BR series	Inductance change : Within $\pm 15\%$	
Test Methods and Remarks	Based on the inductance at 20°C and Measured at the ambient of $-40^{\circ}C \sim +85^{\circ}C$.		

8. Resistance to the	e bendability	
Specified Value	BR series	No damage.
Test Methods and Remarks	Dimension of the board : 100 >	nd then the back side of the board is pushed until it bends 2mm like the figure. × 40 × 1.0mm (0.8mm thickness for 1608(0603) inductors) s epoxy-resin nm
	R5 45±2mm	



9. Body strength			
Specified Value	BR series		No damage.
Test Methods and Remarks	2012~ Applied orce Duration 1608 size Applied force Duration	10N : 10sec. : 5N : 10sec.	

10. Adhesion of terminal electrodes			
Specified Value	BR series	Not to removed from the board.	
Test Methods and	The given sample is soldered to the board and then it is kept for 5sec with 10N stress (5N for 1608(0603) inductors) like the figure.		
Remarks	■ 10N (5N for 1608(0603) inductors		

11. Resistance to vi	bration			
Specified Value	BR series		Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.	
Test Methods and	The given sample is soldered	I to the board ar	nd then it is tested depending on the conditions of the	following table.
Remarks	Vibration Frequency	10~55Hz		
	Total Amplitude	1.5mm (May	y not exceed acceleration 196m/s2)	
	Sweeping Method	10Hz to 55Hz	z to 10Hz for 1min.	
		Х		
	Time Y Z	Y	For 2 hours on each X, Y, and Z axis.	
		Z		
	Recovery : At least 2hrs o	of recovery unde	r the standard condition after the test, followed by the	e measurement within 48hrs.

12. Solderability			
Specified Value	BR series		At least 90% area of the electrodes is covered by new solder.
Test Methods and Remarks	Test Method and Remarks】 The given sample is dipped into the flux and then it is tested depending on the conditions of the following table.		
	Flux : Methanol solution containing rosin 25%.		
	Solder Temperature 245±5°C		
	Time	5±0.5 sec.	

13. Resistance to soldering heat			
Specified Value	BR series	Inductance change : Within \pm 10% No significant abnormality in appearance.	
Test Methods and	3 times reflow having the temperature profile of 5sec of $260+0/-5$ °C and 40sec of more than 230 °C.		
Remarks	Test board thickness : 1.0mm		
	Test board material : Glass epoxy-resin		

14. Thermal shock					
Specified Value	BR serie	s	Inductance change : No significant abnor		
Test Methods and	The give	n sample is soldered to the bo	pard and then its Inductance	s measured after 100cycles of the following conditions.	
Remarks		Conditions of 1	cycle		
	Step Temperature (°C)		Duration (min)		
	1	-40 ± 3	30±3		
	2	Room temperature	Within 3		
	3	$+85\pm2$	30±3]	
	4	Room temperature	Within 3]	

15. Damp heat					
Specified Value	BR series		Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.		
Test Methods and	The given sample is soldered to the board and then it is kept at the following conditions.				
Remarks	Temperature 60±2°C				
	Humidity	90~95%RH			
	Time	1000 hours.			

Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48 hrs.

Specified Value	BR series		Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.
Test Methods and	The given sample is	soldered to the board	and then it is kept at the following conditions.
Remarks	Temperature	60±2°C	
	Humidity	90~95%RH	
	Applied current	Rated current	
	Time	1000hours.	

17. Low temperature life test			
Specified Value	BR series		Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.
Test Methods and	The given sample is soldered to the board and then it is kept at the following conditions.		
Remarks	Temperature	$-40\pm2^{\circ}C$	
	Duration	1000hours	
Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement			— r the standard condition after the test, followed by the measurement within 48 hrs.

18. High temperature life test				
Specified Value	BR series		Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.	
Test Methods and	The given sample is soldered to the board and then it is kept at the following conditions.			
Remarks	Temperature	85±2°C		
	Duration	1000hours		
	Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48 h			

Specified Value BR series Standard test condition : Unless otherwise specified, temperature is 20±15°C and 65±20% of relative humidity. When there is any question concerning measurement result: In order to provide correlation data, the test shall be condition of 20±2°C of temperature, 65±5% relative humidity. Inductance is in accordance with our measured value.	19. Standard conditions		
	Specified Value	BR series	Unless otherwise specified, temperature is $20\pm15^{\circ}$ C and $65\pm20\%$ of relative humidity. When there is any question concerning measurement result: In order to provide correlation data, the test shall be condition of $20\pm2^{\circ}$ C of temperature, $65\pm5\%$ relative humidity.



PRECAUTIONS

1. Circuit Design	
Precautions	 Operating Ambient The products are premised on the usage for the general equipments like the office supply equipment, the telecommunications systems, the measuring equipment, the household equipment and so on. Please ask to TAIYO YUDEN's sales person in advance, if you need to apply them to the equipments or the systems which might have any influences for the human body, the property, like the traffic systems, the safety equipment, the aerospace systems, the nuclear control systems, the medical equipment and soon.

2. PCB Design	2. PCB Design		
Precautions	 ◆Land pattern design 1. Please refer to a recommended land pattern. 		
	◆Land pattern design		
Technical	Surface Mounting		
considerations	1. The conditions of the picking and placing should be checked in advance.		
	2. The products are only for reflow soldering.		

3. Considerations	3. Considerations for automatic placement		
Precautions	 Adjustment of mounting machine 1. Excessive physical impact should not be imposed on the products for picking and placing onto the PC boards. 2. Mounting and soldering conditions should be checked in advance. 		
Technical considerations	♦Adjustment of mounting machine The products might be broken if too much stress is given for the picking and placing.		

4. Soldering	
Precautions	 Reflow soldering Please apply our recommended soldering conditions on the specification as much as possible. The products are only for reflow soldering. Please do not give any stress to a product until it returns in room temperature after reflow soldering. Lead free soldering Please check the adhesion, the solder temperature, the solderability and the shape of solder filet if the solder that is not in the specification is used. Recommended conditions for using a soldering iron (NR10050 Type) Touch a soldering iron to the land pattern not to the product directly. The temperature of a soldering iron is less than 350degC. The soldering is for 3 seconds or less.
Technical considerations	Reflow soldering The product might break or might make the tombstoning, if the soldering conditions are too far from our recommended conditions. 300 5sec max Peak: 200 150~180 90±30sec 30±10sec Heating Time[sec]

5. Cleaning	
Precautions	 ◆Cleaning conditions 1. Please don't wash by the ultra-sonic waves.
Technical	♦ Cleaning conditions
considerations	1. Washing by the ultra-sonic waves might break the product.

6. Handling	
Precautions	 Handling Keep the product away from any magnets. Cutting the PC boards Please don't give any stress of the bending or the twisting for the cutting process of PC boards. Please don't give any shock and stress to the products in transportation. Mechanical considerations Please don't give too much shock to the product. Please don't give any shock and stress to the products in transportation. The stress for picking and placing Please don't give any shock into an exposed ferrite core. Packing Please don't pile the packing boxes up as much as possible.
Technical considerations	 Handling There is a case that a characteristic varies with magnetic influence. Cutting the PC boards Please don't give the bending stress or the twisting stress to the products because they might break in such cases. Mechanical considerations The mechanical shock might break the products. The products might break depending on the handling in transportation. Pick-up pressure The electrical characteristics of the products might be shifted by too much physical shock and stress. Packing The products and the tape might break, if the packing boxes are piled up.
7. Storage condit	
	♦Storage

Precautions	 Storage 1. The packing boxes can be kept at the ambient which the temperature is from 0 to 40degC and the humidity is less than 70%. 2. The ambient temperature of less than 30degC is recommended not to get the tape and the solderability worse. 3. Please solder the products by a half year after they have been shipped. Otherwise please use them after checking the solderability in advance.
Technical considerations	 Storage The ambient of high temperature or high humidity might accelerate to make the solderability and the tape worse.